



K22 THRU K210

2.0 AMP SURFACE MOUNT SCHOTTKY BARRIER RECTIFIERS

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

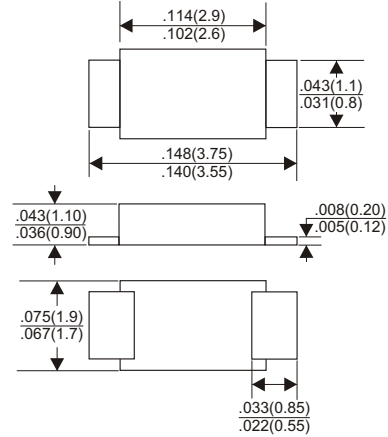
VOLTAGE RANGE

20 to 100 Volts

CURRENT

2.0 Ampere

SOD123FL



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
 Single phase half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

TYPE NUMBER	K22	K23	K24	K25	K26	K28	K29	K210	UNITS
Maximum Recurrent Peak Reverse Voltage	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current	2.0								A
See Fig. 1									
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	40								A
Maximum Instantaneous Forward Voltage at 2.0A	0.55		0.70		0.85				V
Maximum DC Reverse Current Ta=25°C	0.2								mA
at Rated DC Blocking Voltage Ta=100°C	20								mA
Typical Junction Capacitance (Note1)	170								pF
Typical Thermal Resistance R JA (Note 2)	80								°C/W
Operating Temperature Range Tj	-55 — +150						+175		°C
Storage Temperature Range Tstg	-55 — +150								°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Ambient.

RATING AND CHARACTERISTIC CURVES (K22 THRU K210)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

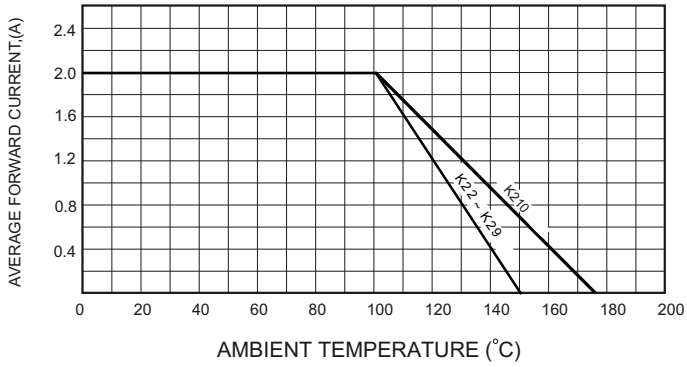


FIG.2-TYPICAL FORWARD CHARACTERISTICS

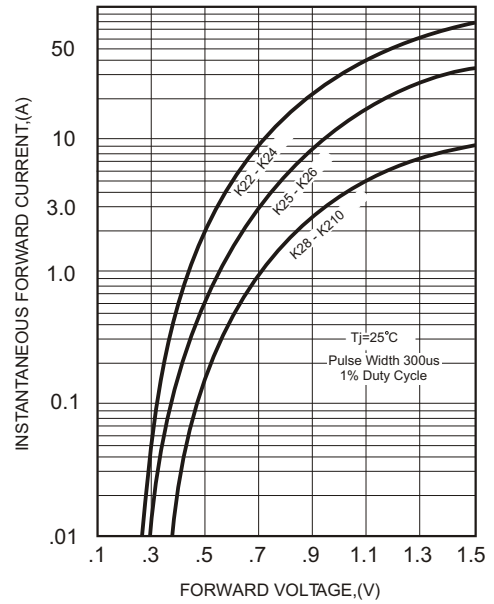


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

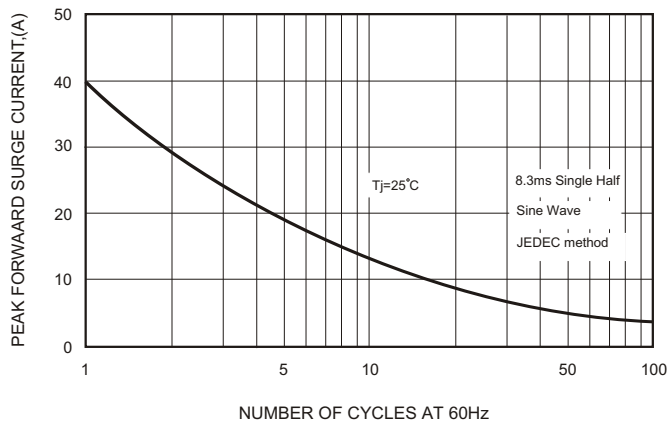


FIG.4-TYPICAL JUNCTION CAPACITANCE

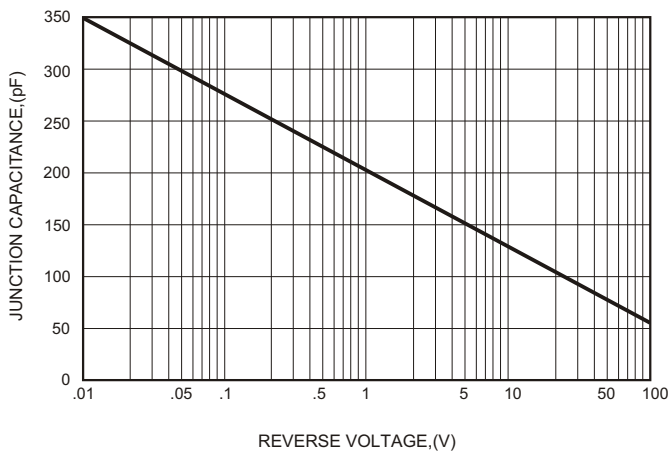
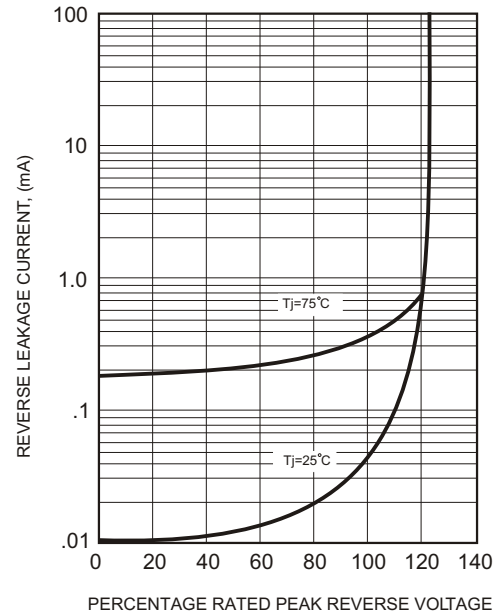


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



Attention:

The graph is for reference only, can't be the basis for judgment.

Any and all information described or contained herein are subject to change without notice due to product/technology improvement.